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**INFORMATION DISCLOSURE
CITATION FORM FOR
PATENT APPLICATION
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(Substitute)**

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Serial No.: 10/700,327

Applicant(s): Paul S. ANDRY et al.

Filing Date: 11/03/03

Group:

U.S. PATENTS

| Initials | Patent Number | Issue Date | Name | Class | Sub-class | Filing date |
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Examiner's Signature: /Mary Wilczewski/

Date Considered: 07/07/2007

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